Date: 10/25/19
Attendees: Michael, Jawad, Reza, Kenneth, Bapi, Quinn, Bapi, Kevin, Rita, Mark, Archna, Lihong, Carrie, Sam, Alex

Agenda:

1. Opens:
    a. Settling in on a path forward for die disaggregation
    b. Feedback form for BoW VDD
    c. Interest in package and test - Synopsys (JTAG within the chip, D2D)
    Present on Friday 11/8/19
    d. Kenneth to post questions to the mailing list, everyone follow up as needed
2. Next Friday 11/:
    a. Workstream updates
    b. Legal updates
3. Chiplet catalog
    a. response from Bill:
        i. we had too many companies claiming conformance to an OCP spec, so we had to create various trademarks. It's expensive and lengthy process to cover WW. But it was the only way to legally stop companies from claiming compliance. The membership agreement was modified to enforce compliance with logo usage and trademarks, as well as the use of the OCP logo. It took a complete cycle of membership renewals before the trademarks and logo usage became effective and enforceable. After that, it has taken 2-3 yr to inform and train the membership.
        ii. A specification comes first. This assures a spec is licensed appropriately, and we go thru a formal voting process to receive a spec into the community. Products that fully comply with a prior released and formally received spec, can apply for the registration mark (OCP ACCEPTED, OCP INSPIRED).
        iii. There are many requirements that they must meet to receive this mark.
        iv. Once they have the cert mark, the suppliers can choose to list on the marketplace. Setting up the marketplace was also lengthy and expensive. We went from a google sheet to track products, to a full CMS system where members can manage the content. An outside company developed the CMS for us (1 yr work effort). This feature was implemented in mid 2019, 3 years after we kicked off the marketplace idea, and 4+ yrs after we started the trademarking and logo usage process.
        v. I don't believe we need quite the expansive dB for chipsets. A chiplet dB has a much smaller audience. We get 5-10K hits/month where someone actually is passed onto the member's OCP landing page. But the legal framework and automation is critical and one of our key learnings.

    b. Jawad: Will chiplets be on the marketplace. Archna - how do silicon products be contributed to the marketplace, how does a portion of a product become OCP compliant
    c. Marketplace participation requires further fees from participants and maintenance support from the OCP. No pricing, lead time - information only. More hits around summit periods.
    d. Start with something lightweight and grow a legal infrastructure as the number of participants grows. Perhaps hang off the wiki
4. ANSYS meeting
    a. Intro meeting to introduce ANSYS to ODSA
    b. ANSYS intends to engage with ODSA. Marketing, CDX initial commits. Could potentially poll their customers.
5. Agenda for the workshop
    a. Eventbrite is not up
    b. Agenda for Dec. 18
        i. Two working sessions - 90 minutes each
            1. Threshold: Significant open issues worth community input.
            2. PoC (lots of prep work needed)
                a. Ratify with a larger group
                    i. Slow speed signals
                    ii. Power sequencing
                    iii. Impact on chiplets
                b. Usage models - who's developing them
            3. Stack discussion focused on the link layer
                a. Choose one abstraction model
                b. Choose selection model
                c. PIPE interface impact on link layer
        ii. Regular group report out
            1. PIPE
            2. BoW (weekly meetings - Wed 9 AM weekly, aim to move to 0.9 spec by December workshop)
            3. CDX (including chiplet directory)
            4. Business
        iii. New ideas - 2 hours
            1. Test session
                a. Based on a proposal from Eelco.
                b. Bill will introduce the HIR test chair. Group developing test challenges. Align with Semi.
            2. Software
                a. Round up participants (Manish, Ashwin + others TBD
            3. Three potential new speakers to be confirmed.